

11. The process according to claim 10, wherein the first device for detecting surface defects and the second device for detecting surface defects are active concurrently during an inspection for another property of the wafer.

12. The process according to claim 10, wherein the wafer rests on at least one supporting member belonging to a transport arm and wherein the ~~method~~ further comprises moving the wafer along a trajectory comprising at least one straight part, and, in the course of the straight part of the trajectory, at least one linear time delay integration camera performs an observation of the top surface of the wafer.

13. The process according to claim 12, in which the inspection is performed before a static inspection.

14. The process according to claim 12, wherein the inspection is performed after a static inspection.

11. The process according to claim 10, wherein the first device for detecting surface defects and the second device for detecting surface defects are active concurrently during an inspection for another property of the wafer.

12. The process according to claim 10, wherein the wafer rests on at least one supporting member belonging to a transport arm and wherein the process further comprises moving the wafer along a trajectory comprising at least one straight part, and, in the course of the straight part of the trajectory, at least one linear time delay integration camera performs an observation of the top surface of the wafer.

13. The process according to claim 12, in which the inspection is performed before a static inspection.

14. The process according to claim 12, wherein the inspection is performed after a static inspection.